## MSKSEMI















**ESD** 

TVS

TSS

MOV

GDT

**PLED** 

# Broduct data sheet



#### **SOT-89**





3. EMITTER



#### **FEATURES**

- Low  $V_{CE(sat)}$ : -0.2V(Typ)  $I_C/I_B$ =-500mA/-50mA
- Compliments 2SD1664

**MAXIMUM RATINGS** (T<sub>A</sub>=25°C unless otherwise noted)

Symbol	Parameter	Value	Units
V <sub>CBO</sub>	Collector-Base Voltage	-40	V
V <sub>CEO</sub>	Collector-Emitter Voltage	-32	V
V <sub>EBO</sub>	Emitter-Base Voltage	-5	V
Ic	Collector Current -Continuous	-1	Α
Pc	Collector Power Dissipation	500	mW
TJ	Junction Temperature	150	℃
T <sub>stg</sub>	Storage Temperature	-55-150	°C

#### ELECTRICAL CHARACTERISTICS (Tamb=25°C unless otherwise specified)

Parameter	Symbol	Test conditions	MIN	TYP	MAX	UNIT
Collector-base breakdown voltage	V <sub>(BR)CBO</sub>	I <sub>C</sub> =-50μA,I <sub>E</sub> =0	-40			V
Collector-emitter breakdown voltage	V <sub>(BR)CEO</sub>	I <sub>C</sub> =-1mA,I <sub>B</sub> =0	-32			V
Emitter-base breakdown voltage	$V_{(BR)EBO}$	I <sub>E</sub> =-50μA,I <sub>C</sub> =0	-5			V
Collector cut-off current	I <sub>CBO</sub>	V <sub>CB</sub> =-20V,I <sub>E</sub> =0			-0.5	μΑ
Emitter cut-off current	I <sub>EBO</sub>	V <sub>EB</sub> =-4V,I <sub>C</sub> =0			-0.5	μA
DC current gain	h <sub>FE</sub>	V <sub>CE</sub> =-3V,I <sub>C</sub> =-100mA	82		390	
Collector-emitter saturation voltage	$V_{\text{CE(sat)}}$	I <sub>C</sub> =-500mA,I <sub>B</sub> =-50mA		-0.2	-0.5	V
Transition frequency	f⊤	V <sub>CE</sub> =-5V,I <sub>C</sub> =-50mA,f=30MHz		150		MHz
Collector output capacitance	$C_{\sf ob}$	V <sub>CB</sub> =-10V,I <sub>E</sub> =0,f=1MHz		20	30	pF

#### CLASSIFICATION OF $h_{\text{FE}}$

Rank	Р	Q	R
Range	82-180	120-270	180-390
Marking	BAP	BAQ	BAR

## **Typical Characteristics**

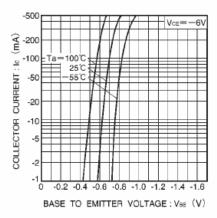
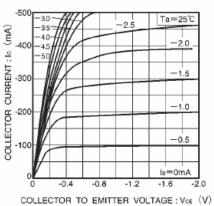


Fig.1 Grounded emitter propagation characteristics



Grounded emitter output characteristics

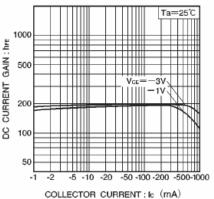
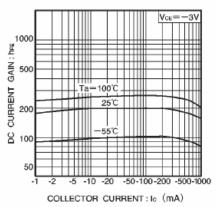


Fig.3 DC current gain vs. collector current (I)



DC current gain vs. Fig.4 collector current (II)

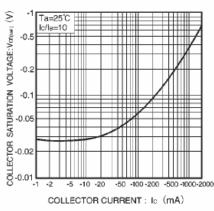
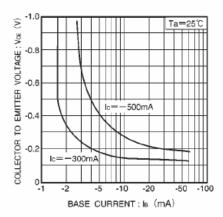


Fig.5 Collector-emitter saturation voltage vs. collector current



Collector-emitter saturation voltage vs. base current

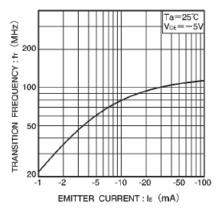


Fig.7 Gain bandwidth product vs. emitter current

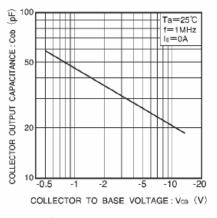


Fig.8 Collector output capacitance vs. collector-base voltage

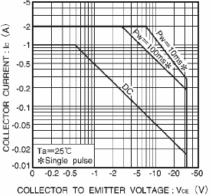


Fig.9 Safe operation area

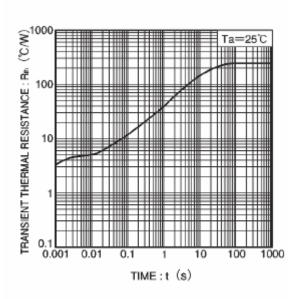
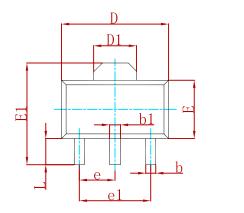
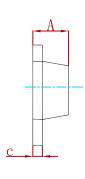


Fig.10 Transient thermal resistance



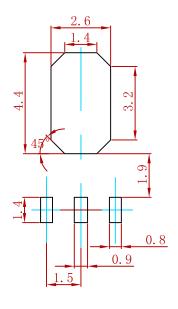
#### **PACKAGE MECHANICAL DATA**





Symbol	Dimensions In Millimeters		Dimensions In Inches		
Зушьог	Min	Max	Min	Max	
Α	1.400	1.600	0.055	0.063	
b	0.320	0.520	0.013	0.020	
b1	0.400	0.580	0.016	0.023	
С	0.350	0.440	0.014	0.017	
D	4.400	4.600	0.173	0.181	
D1	1.550	REF.	0.061	REF.	
E	2.300	2.600	0.091	0.102	
E1	3.940	4.250	0.155	0.167	
е	1.500 TYP.		0.060 TYP.		
e1	3.000 TYP.		0.118 TYP.		
L	0.900	1.200	0.035	0.047	

## Suggested Pad Layout



#### Note:

- 1.Controlling dimension:in millimeters.
- 2.General tolerance:±0.05mm.
- 3. The pad layout is for reference purposes only.

#### **REEL SPECIFICATION**

P/N	PKG	QTY
2SB1132	SOT-89	1000



#### Attention

- Any and all MSKSEMI Semiconductor products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your MSKSEMI Semiconductor representative nearest you before using any MSKSEMI Semiconductor products described or contained herein in such applications.
- MSKSEMI Semiconductor assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specificationsof any andall MSKSEMI Semiconductor products described orcontained herein.
- Specifications of any and all MSKSEMI Semiconductor products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.
- MSKSEMI Semiconductor. strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with someprobability. It is possiblethat these probabilistic failures could give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits anderror prevention circuitsfor safedesign, redundant design, and structural design.
- In the event that any or all MSKSEMI Semiconductor products(including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from theauthorities concerned in accordance with the above law.
- No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of MSKSEMI Semiconductor.
- Information (including circuit diagrams and circuit parameters) herein is for example only; it is not guaranteed for volume production. MSKSEMI Semiconductor believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringementsof intellectual property rights or other rightsof third parties.
- Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. Whendesigning equipment, referto the "Delivery Specification" for the MSKSEMI Semiconductor productthat you intend to use.

### **X-ON Electronics**

Largest Supplier of Electrical and Electronic Components

Click to view similar products for Bipolar Transistors - BJT category:

Click to view products by MSKSEMI manufacturer:

Other Similar products are found below:

BC559C MCH4017-TL-H MMBT-2369-TR BC546/116 NJVMJD148T4G NTE16 NTE195A IMX9T110 2N4401-A 2N4403 2N6728

2SA1419T-TD-H 2SA2126-E 2SB1204S-TL-E FMC5AT148 2N2369ADCSM 2N2907A 2N3904-NS 2N5769 2SC4618TLN CPH6501
TL-E MCH4021-TL-E Jantx2N5416 US6T6TR BAX18/A52R BC556/112 IMZ2AT108 MMST8098T146 UMX21NTR MCH6102-TL-E

TTA1452B,S4X(S 2N3879 NTE13 NTE282 NTE323 NTE350 NTE81 JANTX2N2920L JANTX2N3735 JANSR2N2222AUB

CMLT3946EG TR SNSS40600CF8T1G CMLT3906EG TR GRP-DATA-JANS2N2907AUB GRP-DATA-JANS2N2222AUA

MMDT3946FL3-7 2N4240 JANS2N3019 MSB30KH-13 2N2221AUB